Title (en)

Process of upsetting a billet by hot working, method for preparing a billet to a forging operation according to said process and apparatus for carrying out said process

Title (de)

Verfahren zum Stauchen eines metallischen Rohlings durch Warmverarbeitung, Verfahren zur Vorbereitung eines Rohlings für ein Schmiedeverfahren gemäss dem Stauchverfahren und Vorrichtung zur Durchführung des Stauchverfahrens.

Title (fr)

Procédé de refoulage pour le corroyage d'un lopin métallique, procédé de préparation d'un lopin à une opération de forgeage selon le procédé et dispositif de mise en oeuvre du procédé

Publication

EP 1652599 A1 20060503 (FR)

Application

EP 05110155 A 20051028

Priority

FR 0452483 A 20041029

Abstract (en)

The redressing for the welding of a metal piece (14), presenting a determined thinning, consists of arranging the piece longitudinally, at least partially, in a cylindrical housing (3) of a redressing pot (2) and exerting a pressure on the piece in the longitudinal direction by means of a punch (10) until the piece fills the whole section of the housing. This reduces the thinning of the piece and a cylindrical piece with a section equal to that of the housing is obtained, in preparation for a forging operation. An independent claim is also included for the redressing device used by this method of redressing a thinned piece.

IPC 8 full level

B21J 5/08 (2006.01)

CPC (source: EP US)

B21J 5/008 (2013.01 - EP US); **B21J 5/08** (2013.01 - EP US)

Citation (search report)

- [XA] US 4312210 A 19820126 - NISHIZAWA MASATOSHI, et al
- [A] DE 19911118 A1 19990930 - SOC D MECANIQUE ET DE PLASTIQU [FR], et al
- [A] DE 2161543 A1 19720706

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

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DOCDB simple family (application)

EP 05110155 A 20051028; CN 200510117072 A 20051031; DE 602005001600 T 20051028; FR 0452483 A 20041029; JP 2005312531 A 20051027; RU 2005133389 A 20051028; US 26014305 A 20051028